

# OL-NTB0104UK

wafer level chip-size package, 12 bumps

8 February 2016

Package information

## 1. Package summary

|                                       |                     |
|---------------------------------------|---------------------|
| <b>Terminal position code</b>         | B (bottom)          |
| <b>Package type descriptive code</b>  | WLCSP               |
| <b>Package type industry code</b>     | WLCSP               |
| <b>Package style descriptive code</b> | UC (uncased chip)   |
| <b>Package style suffix code</b>      | NA (not applicable) |
| <b>Package body material type</b>     | X (other)           |
| <b>IEC package outline code</b>       | ---                 |
| <b>JEDEC package outline code</b>     | ---                 |
| <b>JEITA package outline code</b>     | ---                 |
| <b>Mounting method type</b>           | S (surface mount)   |
| <b>Issue date</b>                     | 16-6-2011           |

Table 1. Package summary

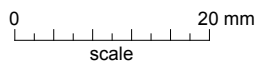
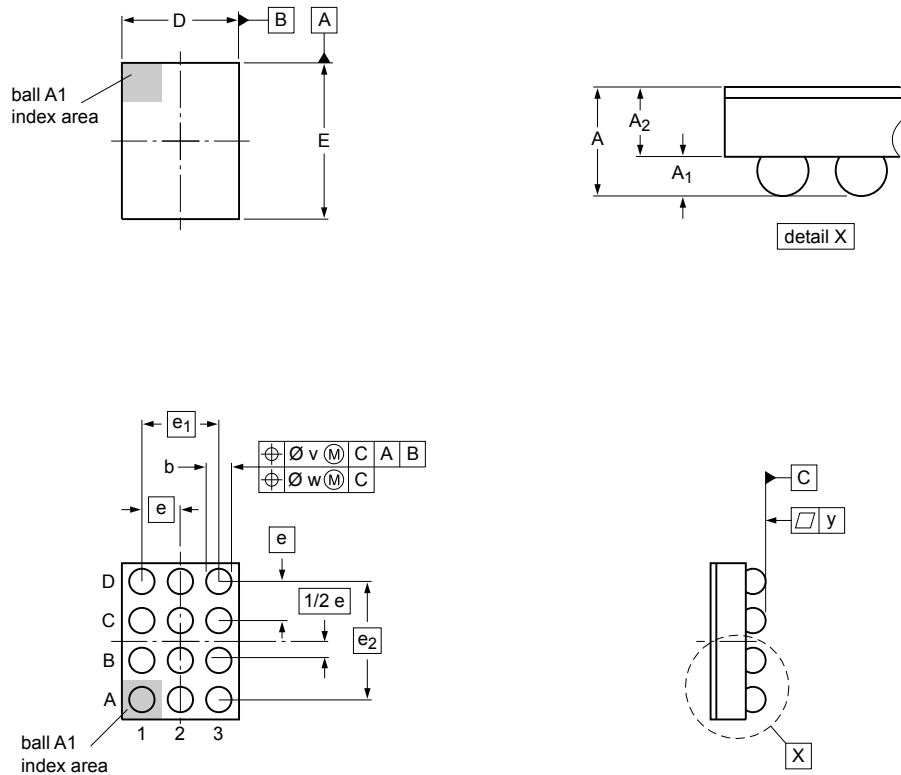
| Symbol         | Parameter                      | Min   | Typ | Nom  | Max   | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| D              | package length                 | 1.17  | -   | 1.2  | 1.23  | mm   |
| E              | package width                  | 1.57  | -   | 1.6  | 1.63  | mm   |
| A              | seated height                  | 0.505 | -   | 0.56 | 0.615 | mm   |
| A <sub>2</sub> | package height                 | 0.335 | -   | 0.36 | 0.385 | mm   |
| e              | nominal pitch                  | -     | -   | 0.4  | -     | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 12   | -     |      |



## 2. Package outline

WLCSP12: wafer level chip-size package,  
12 bumps; body 1.20 x 1.60 x 0.56 mm. (Backside Coating included)

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Dimensions

| Unit | A     | A <sub>1</sub> | A <sub>2</sub> | b    | D    | E    | e    | e <sub>1</sub> | e <sub>2</sub> | v    | w     | y    |
|------|-------|----------------|----------------|------|------|------|------|----------------|----------------|------|-------|------|
| max  | 0.615 | 0.23           | 0.385          | 0.29 | 1.23 | 1.63 |      |                |                |      |       |      |
| nom  | 0.560 | 0.20           | 0.360          | 0.26 | 1.20 | 1.60 | 0.40 | 0.80           | 1.20           | 0.05 | 0.015 | 0.03 |
| min  | 0.505 | 0.17           | 0.335          | 0.23 | 1.17 | 1.57 |      |                |                |      |       |      |

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| Outline version | References |       |       | European projection | Issue date             |
|-----------------|------------|-------|-------|---------------------|------------------------|
|                 | IEC        | JEDEC | JEITA |                     |                        |
| NTB0104UK       |            |       |       |                     | -11-05-23-<br>11-06-16 |

Fig. 1. Package outline WLCSP (OL-NTB0104UK)

### 3. Legal information

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